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Atty Ref/Docket No.: 884.943US1



Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks 102495176

ached original documents or copy thereof

1. Name of conveying party(ies):
Kum Foo Leong, Siew Fong Tai and Chee Key Chung

2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2200 Mission College Blvd.

City: Santa Clara State: CA Zip: 95052

Additional name(s) & address(es) attached? []Yes [X]No

Additional name(s) of conveying party(ies) attached?
[]Yes [X]No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Execution Date: June 30, 2003, June 30, 2003, June 30, 2003



4. Application number(s) or patent number(s): 10,610,168

If this document is being filed together with a new application, the execution date of the application is: June 30, 2003

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? []Yes [X]No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Richard E. Billion

Address:
Schwegman, Lundberg, Woessner & Kluth, P.A.
P.O. Box 2938
Minneapolis, MN 55402

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):\$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Please charge any additional fees or credit any over payments to our Deposit account number: 19-0743

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Richard E. Billion/Reg. No. 32,836
Name of Person Signing

Richard E. Billion
Signature

6/30/03
Date

07/11/2003 BY: 00000075 10610168

Total number of pages including cover sheet: 3

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Mail documents to be recorded with required cover sheet information to:

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PATENT
REEL: 014246 FRAME: 0936

ASSIGNMENT

WHEREAS, We, Kum Foo Leong, residing at 819 Lot 5, Batu 6, Lunas Kulim, Kedah, 09600, and Siew Fong Tai, residing at CS 24 A, 43300 Seri Kembangan, Selangor., and Chee Key Chung, residing at 103-18-8, Persiaran Bukit Gambier 1, Gelugor, Penang, 11700, made certain new and useful inventions and improvements for which we executed an application for Letters Patent of the United States on even date herewith, which is entitled SOLDER INTERFACE LOCKING USING UNIDIRECTIONAL GROWTH OF INTERMETALLIC COMPOUND;

AND WHEREAS, Intel Corporation, a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 2200 Mission College Blvd., Santa Clara, CA 95052 (hereinafter "Assignee"), is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefor;

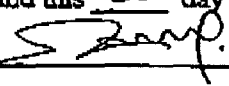
NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted there from, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted there from; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

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AND, for the consideration aforesaid, we do hereby agree that we and our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore, we covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by us and that full right to convey the same as herein expressed is possessed by us.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 30 day of JUNE, 2003.



Kum F. Leong

IN TESTIMONY WHEREOF, I have hereunto set my hand this 30 day of June, 2003.



Siew F. Tai

IN TESTIMONY WHEREOF, I have hereunto set my hand this 30 day of June, 2003.



Chee K. Chung